

/ Revised record

H	2018-4				
A	2022-5-24	all	BR Q AEC-Q101 , H Q 245 ±5°C 5±0.5sec 255±5°C 5±0.5sec		

/ Descriptions

SOD-323

Silicon Diode in a SOD-323 Plastic Package.

/ Features

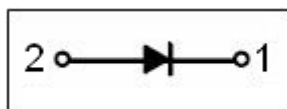
AEC-Q101

Small signal diode, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

/ Applications

Switching diodes, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit



/ Pinning



PIN1:Cathode

PIN2:Anode

/ Marking

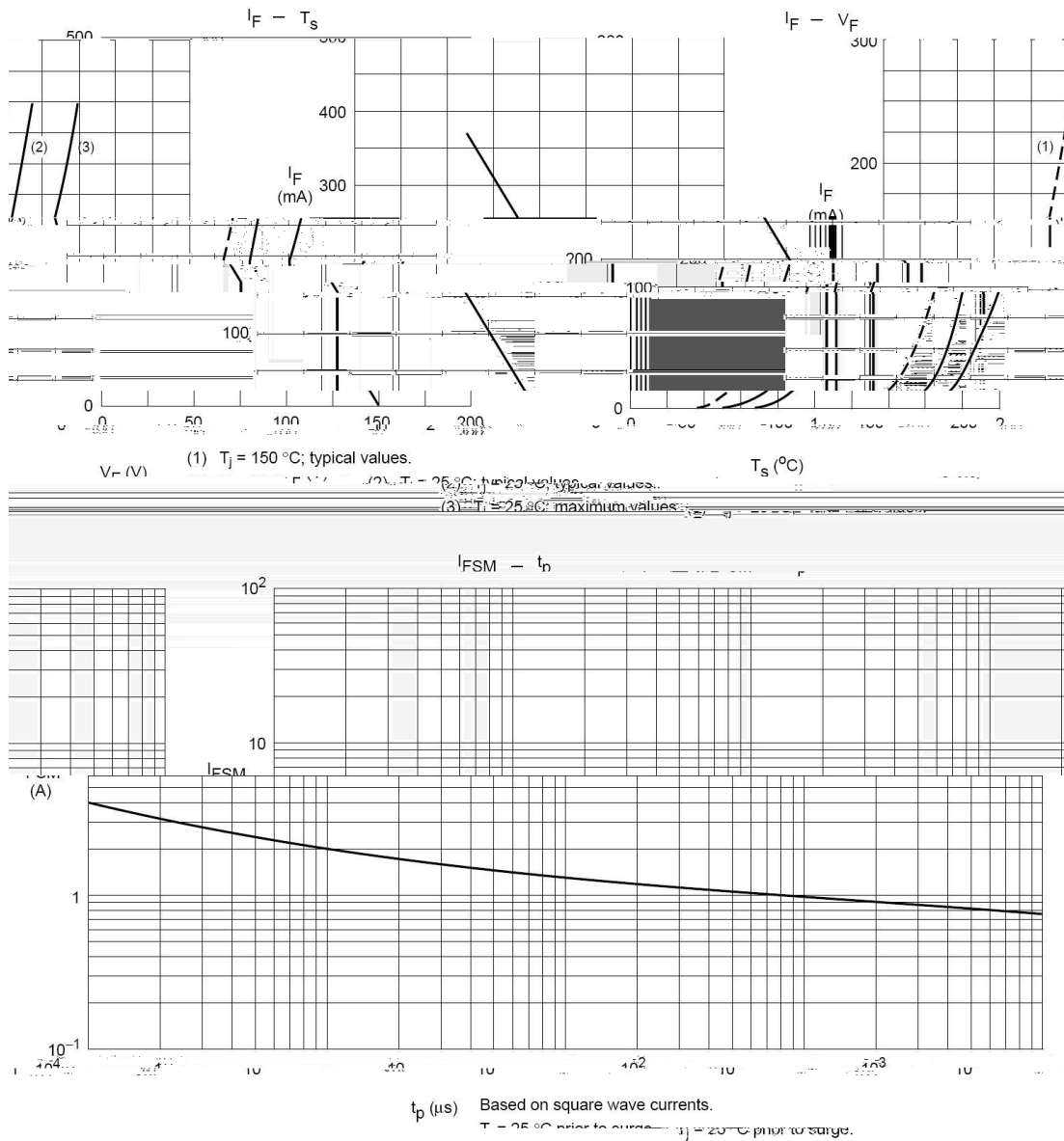
Marking	A6Q
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BRBAS316Q

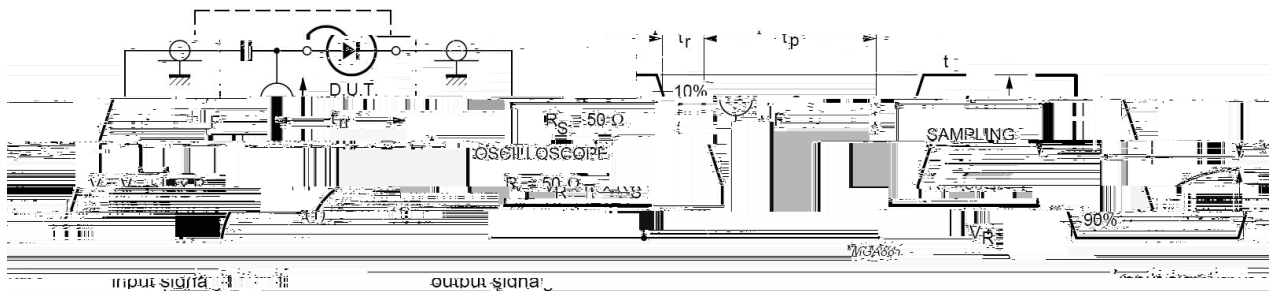
Rev.A



/ Electrical Characteristic Curve



/ Test circuit and waveforms.



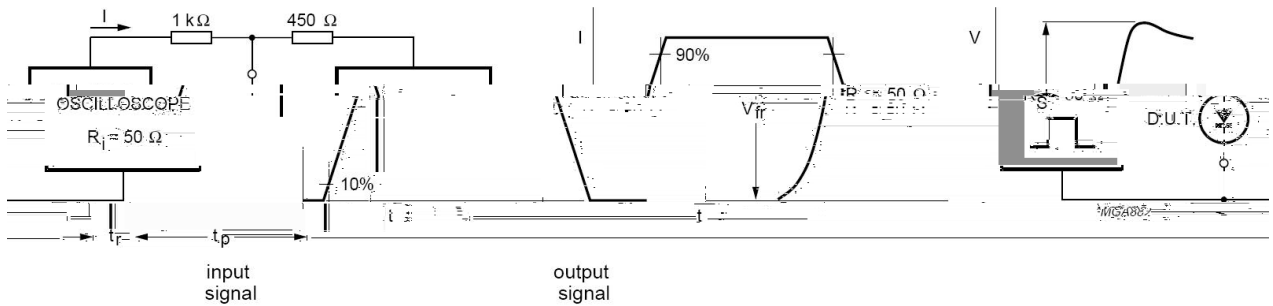
pulse duration $t_p = 100$ ns; duty factor $\delta = 0.05$;

oscilloscope rise time $t_r = 0.35$ ns.

(1) $I_R = 1$ mA.

Input signal: reverse pulse rise time $t_r = 0.6$ ns; reverse voltage

oscilloscope rise time $t_r = 0.35$ ns.

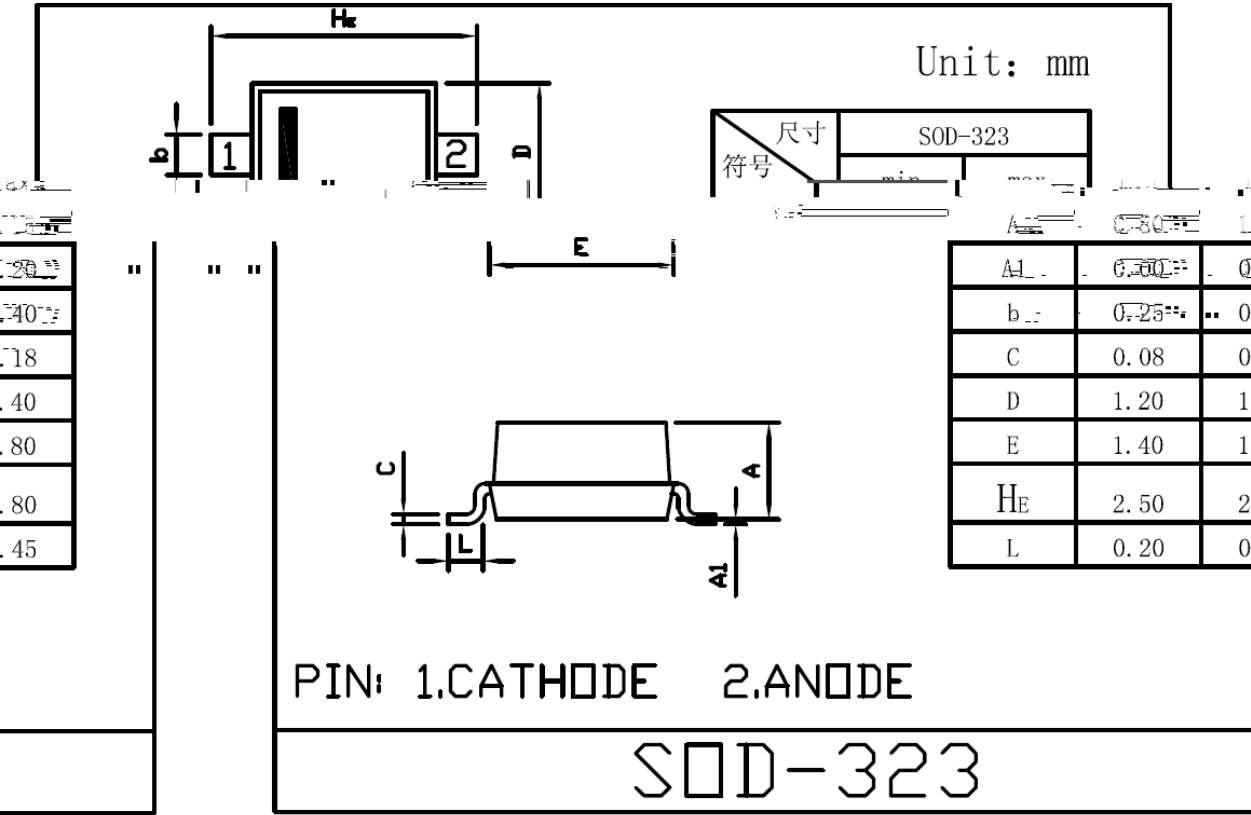


forward pulse rise time $t_r = 20$ ns; forward current pulse duration $t_p > 100$ ns; duty factor $\delta < 0.005$

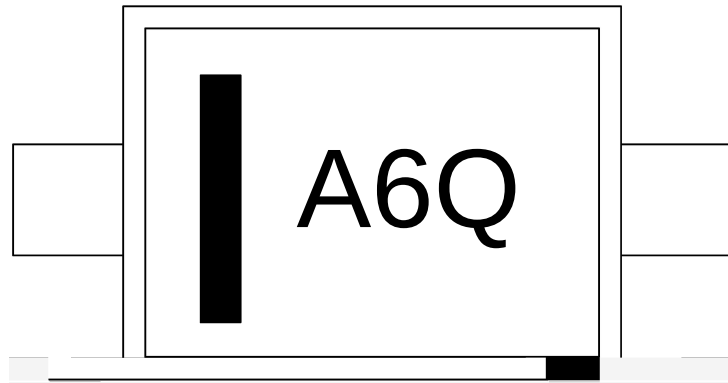
Input signal: f



/ Package Dimensions



/ Marking Instructions



说明：

A6： 为型号代码

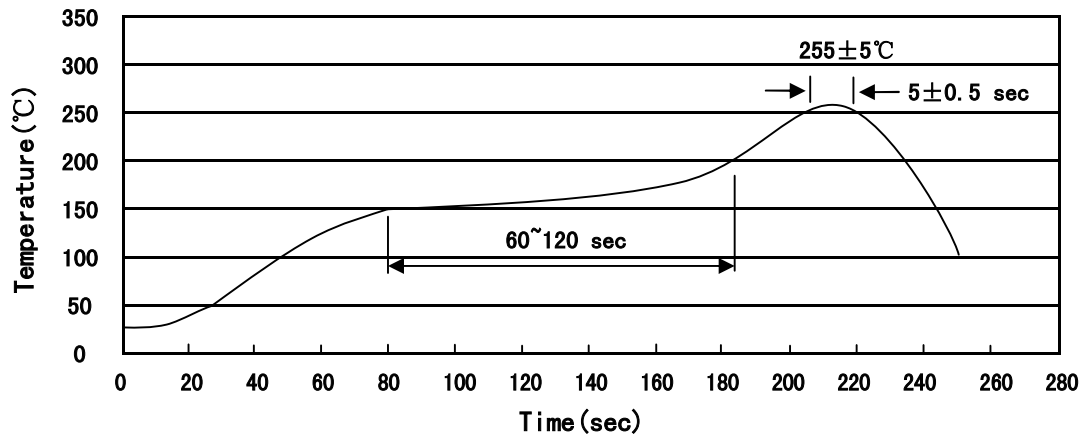
Q： 为汽车无卤产品标识

Note:

A6: Product Type Code

Q: Automobile halogen-free product Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 150 200 60 120sec; 1.Preheating:150~200 , Time:60~120sec.
- 255±5 5±0.5sec; 2.Peak Temp.:255±5 , Duration:5±0.5sec.
- 2 10 /sec. 3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOD-323	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices